Corporate Fact Sheet
May 2009

Tessera is a technology innovator that develops and delivers miniaturization solutions that transform electronic products in areas such as next-generation wireless, consumer and computing. The company's packaging and interconnect solutions offer new levels of semiconductor miniaturization by enabling smaller, higher-functionality electronic devices. Its imaging and optics solutions provide low-cost, high-quality camera functionality in electronic products, and include image sensor packaging, wafer-level optics and "smart" image enhancement intellectual property (IP). The company also offers customized micro-optic lenses, from digital and refractive optical elements to integrated micro-optical sub-assemblies. Tessera licenses its innovations, as well as delivers products based on these innovations to promote the development of the supply chain infrastructure, enabling manufacturers to get the right product to market, at the right time.

At A Glance:

- Company Founded: 1990
- Revenue for FY 2008: $248.3 million
- Employees for FY 2008: 415: 60% technologists, of which 20% have PhDs
- Headquarters: 3025 Orchard Parkway, San Jose, Calif. 95134
- Locations: Sales, support and R&D offices worldwide in North America, Europe, Israel, Japan and Asia Pacific

Management Team:

- Henry R. "Hank" Nothhaft, President and CEO
- Michael Anthofer, Executive Vice President and CFO
- Robert Yung, Executive Vice President and CTO
- John Keating, Senior Vice President, Corporate Development
- Michael Bereziuk, Executive Vice President, Imaging & Optics
- Craig Mitchell, Senior Vice President, Interconnect, Components & Materials, Micro-electronics
- Brian Marcucci, Senior Vice President, Business Development & Licensing, Micro-electronics
- Bernard J. "Barney" Cassidy, Senior Vice President and General Counsel
- H. Thomas Blanco**,** Senior Vice President and Chief Administration Officer

Solutions

Tessera invests in, develops and delivers a comprehensive portfolio of technologies in:

- Micro-electronics – semiconductor packaging technologies encompassing interconnect and substrates, and thermal management solutions including
  - µPILR™ interconnect platform
  - µBGA® family of lead- and wire-bonded chip-scale packages (CSPs)
  - µZ® Multi-Chip Package (MCP) technology
- Imaging and optics - wafer-level optics, image sensor packaging and smart image enhancement technologies, and micro-optic solutions
  - OptiML™ wafer-level camera (WLC) and image enhancement solutions
  - FotoNation® embedded imaging solutions for digital still and cell phone cameras
  - SHELLCASE® wafer-level, chip-scale (WLCS) image-sensor packaging technology
  - DigitalOptics™ diffractive and refractive optical elements and integrated multi-optical sub-assemblies